IN THE SPECIFICATION:

Please replace the first full paragraph on page 8 with the following amended paragraph:

As shown in Figures 3(a)-(b) ~~4(a)-(d)~~, adapter 300 generally comprises a substrate 301, a sensor metallization 309 provided on an upper surface portion of substrate 301, and a ground metallization 310 provided on a lower surface portion of substrate 301. Sensor metallization 309 acts as a passive capacitive signal detector for detection of signals and current generated by the secondary coil of the coil-on plug. Cable 318 conducts signals detected by sensor metallization 309 to other equipment, such as a digital signal analyzer (e.g., a Snap-On Vantage KV Module (EETM306A) or Snap-On MODIS™ system).

Please replace the second full paragraph on page 8 with the following amended paragraph:

A protective material or sheath (not shown), such as an epoxy or polymer sealant, may also optionally be provided on one or both metallizations 309, 310 or to the wiring metallizations 311 electrically connected thereto to retard or prevent corrosion or inadvertent grounding of the sensor metallization or associated wiring metallization. As shown in Figures 4(a)-(d), an ~~An~~ attachment device 320 by which the adapter is secured to a coil-on plug housing (e.g., 500) is also provided, as is a sensor displacement assembly 329 which controls the displacement of the sensor metallization 309 from the coil-on plug housing.